

A

B

C

D

A

B

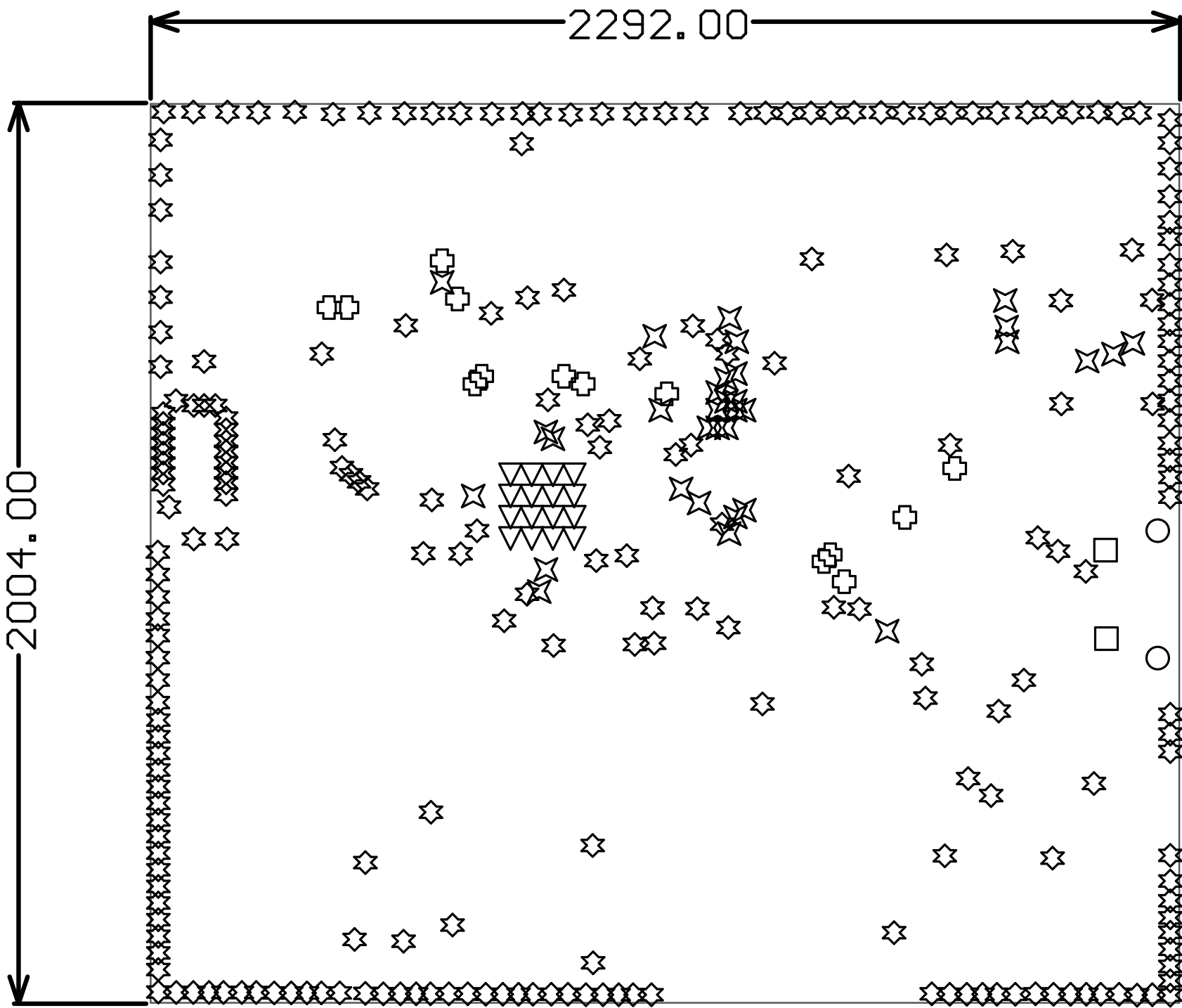
C

D

Symbol	Count	Hole Size	Plated	Hole Type	Hole Length	Routed Path Length
○	2	32.48mil (0.825mm)	PTH	Slot	59.06mil (1.500mm)	26.57mil (0.675mm)
□	2	35.43mil (0.900mm)	PTH	Slot	39.37mil (1.000mm)	3.94mil (0.100mm)
⊕	14	7.00mil (0.178mm)	PTH	Round	-	-
▽	16	12.99mil (0.330mm)	PTH	Round	-	-
✕	33	6.00mil (0.152mm)	PTH	Round	-	-
☆	236	8.00mil (0.203mm)	PTH	Round	-	-
	303 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack	Board Layer Stack
1	Top Overlay					
2	Top Solder	Solder Resist	0.40mil	3.5		
3	Top	Copper	1.40mil			
4	Core 1	FR-4	5.00mil	4.2		
5	Layer 2	Copper	0.70mil			
6	Core 2	FR-4	10.00mil	4.2		
7	Layer 3	Copper	0.70mil			
8	Core 3	FR-4	5.00mil	4.2		
9	Bottom	Copper	1.40mil			
10	Bottom Solder	Solder Resist	0.40mil	3.5		
11	Bottom Overlay					



- NOTES: UNLESS OTHERWISE SPECIFIED
1. MATERIAL: COPPER CLAD PLASTIC SHEET PER IPC-4101
ROHS COMPLIANT TG 140 FR-4
TYPE GFN FINISHED COPPER WEIGHT TO BE: 1 OZ.
OVERALL BOARD THICKNESS TO BE .025 +/- .005.
 2. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS
APPLY AFTER PLATING.
 3. ALL HOLES SHALL BE LOCATED WITHIN 0.003 DIAMETER OF
TRUE POSITION. LAYER TO LAYER REGISTRATION SHALL BE
WITHIN 0.003. ADD TEARDROPS AS REQUIRED SO THAT ALL
HOLES SURROUNDED BY LAND SHALL HAVE A MINIMUM ANNULAR
RING OF 0.002.
 4. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 20%
OF ARTWORK ORIGINALS.
 5. APPLY SOLDERMASK (LIQUID PHOTO IMAGEABLE) OVER BARE
COPPER, SOLDERMASK TO BE PER IPC-SM-840, CLASS T,
COLOR: TRANSPARENT GREEN. ALL EXPOSED CONDUCTIVE
SURFACES TO BE IMMERSION GOLD OVER ELECTROLESS NICKEL
(ENIG) PER IPC-4552.
 6. WARP OR TWIST OF BOARD SHALL NOT EXCEED 0.75%.
 7. APPLY SILKSCREEN, AS REQUIRED, USING WHITE EPOXY INK.
 8. REMOVE ALL BURRS AND BREAK SHARP EDGES 0.001 MAX.
 9. FABRICATE IN ACCORDANCE WITH IPC-6012, TYPE 2, CLASS 2.
 10. DIMENSIONS AND TOLERANCES PER ANSI Y14.5.
 11. SURFACE MOUNT PAD SOLDER PLATING MUST BE FLAT TO A
MAXIMUM OF 0.001 ABOVE BOARD SURFACE.
 12. ALL COPPER SET BACK MUST BE MAINTAINED WITHIN ARTWORK
ORIGINALS FROM ANY EDGE OF P.C. BOARD (i.e O.D., I.D,
NON-PLATED THROUGH HOLES, NON-PLATED RADIUS, GROOVES
AND SLOTS).
 13. ALL VIAS TO BE TENTED UNLESS EXPLICITLY CLEARED IN GERBERS
 14. DO NOT CHANGE GERBERS WITHOUT WRITTEN APPROVAL

Jewelbots, Inc. 50 Eldridge St. 5th Floor New York, NY 10002	ENGINEER: S. Dandona	TITLE: Dev. Board Fab Drawing	
	PCB DESIGNER: S. Dandona		
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